

# SOT804-1

plastic thermal enhanced very thin quad flat package; no leads; 64 terminals; body 9 x 9 x 0.85 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN64
<b>Package type industry code</b>	HVQFN64
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-220
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	26-3-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	8.95	-	9	9.05	mm
E	package width	8.95	-	9	9.05	mm
A	seated height	[tbd]	-	0.85	1	mm
A <sub>2</sub>	package height	[tbd]	-	0.85	[tbd]	mm
n <sub>2</sub>	actual quantity of termination	-	-	64	-	

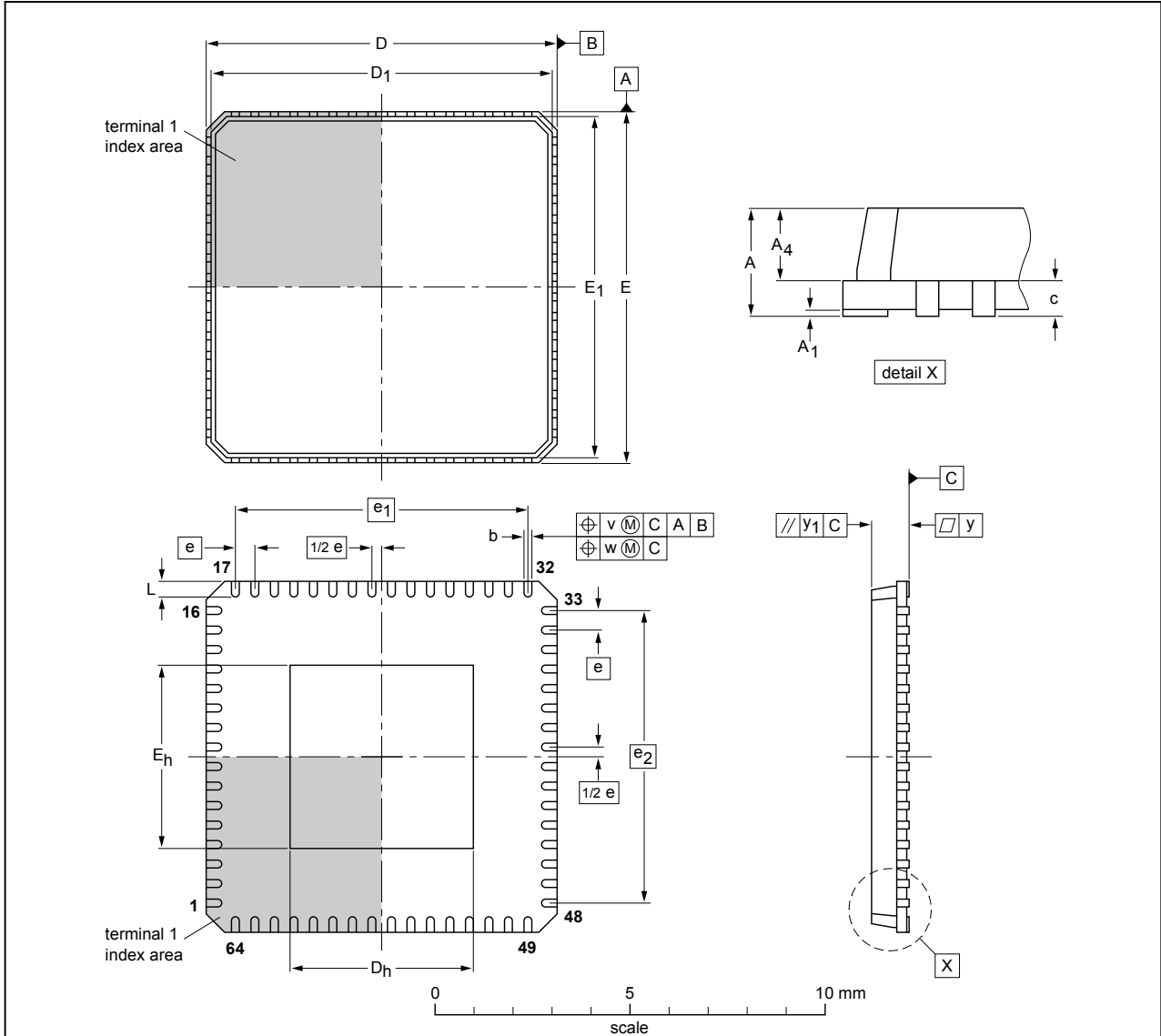


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## 2. Package outline

HVQFN64: plastic thermal enhanced very thin quad flat package; no leads; 64 terminals; body 9 x 9 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>4</sub>	b	c	D	D <sub>1</sub>	D <sub>h</sub>	E	E <sub>1</sub>	E <sub>h</sub>	e	e <sub>1</sub>	e <sub>2</sub>	L	v	w	y	y <sub>1</sub>
mm	1	0.05 0.00	0.80 0.65	0.30 0.18	0.2	9.05 8.95	8.95 8.55	4.85 4.55	9.05 8.95	8.95 8.55	4.85 4.55	0.5	7.5	7.5	0.5 0.3	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT804-1	---	MO-220	---			03-03-26

Fig. 1. Package outline HVQFN64 (SOT804-1)

plastic thermal enhanced very thin quad flat package; no leads; 64 terminals; body 9 x 9 mm  
0.85 mm

### 3. Soldering

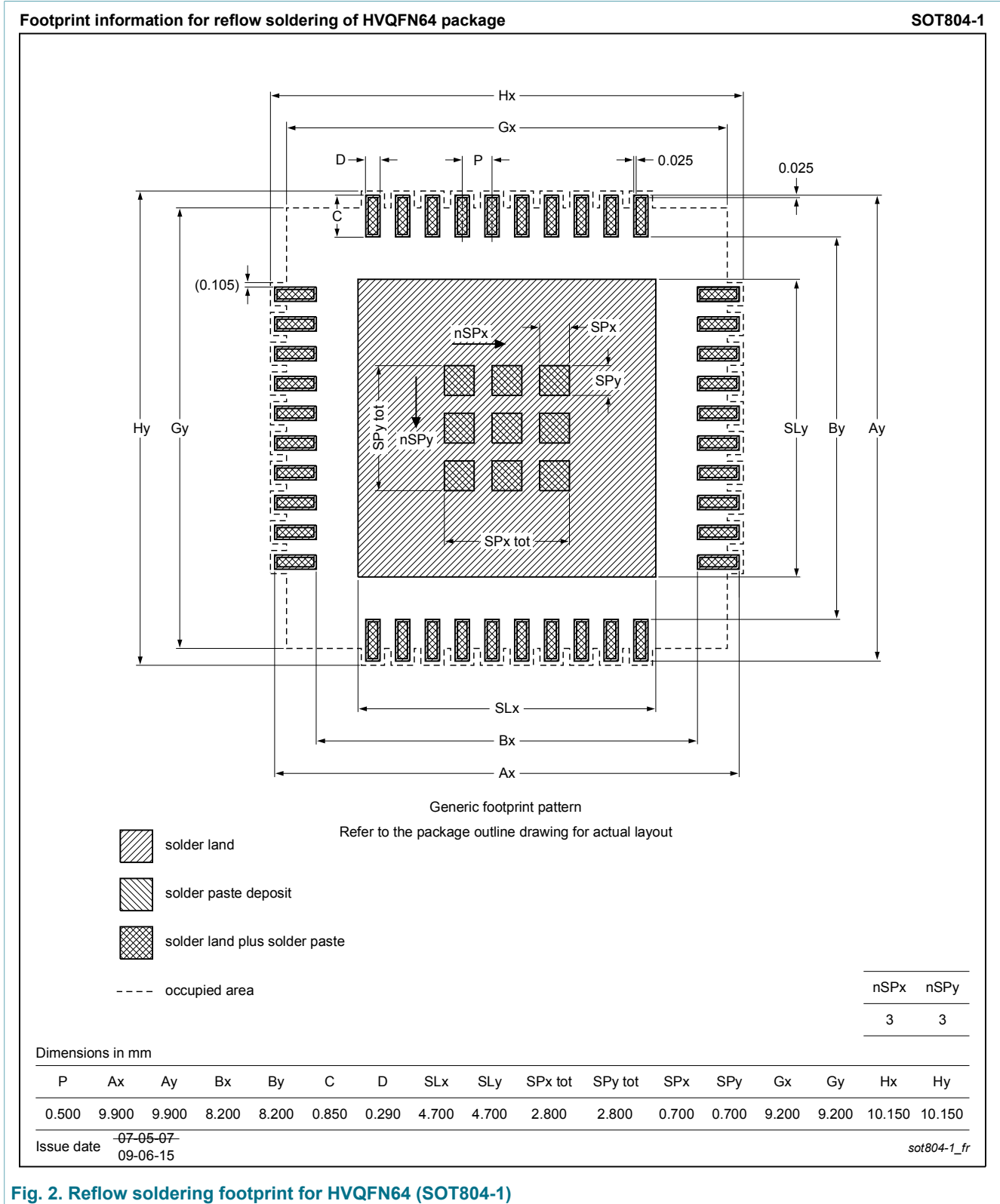


Fig. 2. Reflow soldering footprint for HVQFN64 (SOT804-1)

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## 4. Legal information

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